

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	2	"11082150"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/17 01:13
S2	1	"11/082150"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/19 11:04
S3	3829	257/787.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/17 01:20
S4	216	S3 and plasma	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/17 01:21
S5	2234435	substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/19 17:00
S6	3444262	sealing adj compound (encapsula\$3 encapsulation mold\$3 resin epoxy potting gel)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/17 12:37
S7	18436	S6 with plasma	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/17 01:24
S8	7527	S6 near5 plasma	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/17 01:24
S9	901	S6 near5 (plasma near3 treat\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/17 01:27

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S10	2	(sealing adj compound) near5 (plasma near3 treat\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/17 01:26
S11	700	S6 near3 (plasma near3 treat\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/17 12:37
S12	46	S11 with (chip device element)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/17 12:38
S13	0	("6707167").URPN.	USPAT	OR	OFF	2006/09/17 09:19
S14	5	("5659952" "6218215" "6489675" "6518662" "6602740").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/09/17 09:19
S15	3444262	sealing adj compound (encapsula\$3 encapsulation mold\$3 resin epoxy potting gel)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/17 12:37
S16	700	S15 near3 (plasma near3 treat\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/17 12:37
S17	46	S16 with (chip device element)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/17 12:38
S18	891	257/788.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/19 10:04
S19	3445415	sealing adj compound (encapsula\$3 encapsulation mold\$3 resin epoxy potting gel)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/19 10:02
S20	700	S19 near3 (plasma near3 treat\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/19 18:21

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S21	0	S18 and S20	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/19 10:04
S22	6	"6790706".pn. "6951773".pn. "6632704".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/19 10:05
S23	1	11/082150	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/19 13:51
S24	2	"20020038918"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/09/19 15:34
S25	2	"6992326".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/09/19 15:52
S26	323	substrate near3 release adj film	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/23 16:23
S27	1	S20 and S26	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/19 17:01
S28	527	substrate near10 release adj film	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/19 17:01
S29	1	S20 and S28	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/19 17:02
S30	9314	substratewith release adj film	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/19 17:18

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S31	2	S20 and S30	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/19 17:19
S32	1075	substrate with release adj film	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/19 17:18
S33	2	S20 and S32	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/19 17:19
S34	842	S19 and S32	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/19 17:20
S35	334	S19 with S32	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/19 19:23
S36	1377646	(rug\$4 rough\$4 asperit\$4 hillock) (non adj uniform\$4 nonuniform\$4 porous\$4 pore)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/19 18:22
S37	1378295	(rug\$4 rough\$4 asperit\$4 hillock) (non adj uniform\$4 nonuniform\$4 porous\$4 pore minute adj projection)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/19 18:01
S38	126148	S19 with S37	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/19 18:02
S39	52603	S19 near3 S37	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/19 18:02
S40	18229	S19 near S37	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/19 18:02

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S41	119	substrate near release adj film	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/19 18:03
S42	0	S40 same S41	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/19 18:04
S43	0	S40 and S41	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/19 18:04
S44	3434	S40 and (die chip)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/19 18:04
S45	2422	S40 and (die chip) and (mold seal\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/19 19:42
S46	37	S40 and (die chip) and ((mold seal\$4) near compound)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/19 18:09
S47	1	(minute near projection) and ((mold seal\$4) near compound)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/19 18:09
S48	2	S40 near3 (plasma near3 treat\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/19 18:22
S49	827250	(rug\$4 rough\$4 asperit\$4 hillock) (non adj uniform\$4 nonuniform\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/19 18:22
S50	76	S49 near3 (plasma near3 treat\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/19 18:42

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S51	17	S49 near5 (plasma near3 treat\$3) with substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/19 18:42
S52	64	S35 with (die chip encapsulat\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/23 16:27
S53	52	S35 with (chip element encapsulat\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/19 19:35
S54	7	S53 not S52	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/19 19:35
S55	766	(substrate near release) and (die chip) and (mold seal\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/19 19:42
S56	37	(substrate near (release adj film)) and (die chip) and (mold seal\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/19 19:48
S57	37	S56 not S46	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/19 19:43
S58	28	(substrate adj (release adj film)) and (die chip) and (mold seal\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/19 20:25
S59	13	(substrate adj (release adj film)) with (die chip)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/19 19:58
S60	3	(substrate adj (release adj film)) with (element chip)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/19 19:57

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S61	3	(substrate adj (release adj film)) with (ic chip)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/19 19:57
S62	68	(substrate with (release adj film)) with (die chip)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/19 20:05
S63	0	stack\$3 near chip with release adj film	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/19 20:06
S64	0	(stack\$3 near chip) with (release adj film)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/19 20:06
S65	1	(stack\$3 near5 chip) with (release adj film)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/19 20:06
S66	3	(stack\$3 near20 chip) with (release adj film)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/19 20:07
S67	1	(stack\$3 near3 chip) same (release adj film)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/19 20:07
S68	19	(stack\$3 near3 chip) and (release adj film)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/19 20:07
S69	860	substrate and (release adj film) and (die chip) and (mold seal\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/19 20:28
S70	85	substrate and (release adj film) and (die chip) and (mold seal\$4) and encapsul\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/19 20:28

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S71	52104	substrate near3 (superstress bonding release adj film)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/23 16:24
S72	36583	substrate near2 (superstress bonding release adj film)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/23 16:24
S73	16427	substrate near (superstress bonding release adj film)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/23 16:29
S74	3447372	sealing adj compound (encapsula\$3 encapsulation mold\$3 resin epoxy potting gel)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/23 16:25
S75	1702	S73 with S74	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/23 16:30
S76	373	S75 with (die chip encapsulat\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/23 16:27
S77	182	substrate near (superstress release adj film)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/23 16:29
S78	41	S77 with S74	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/23 16:30
S79	182	substrate near (superstress release adj film)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/24 00:06
S80	1369	310/313r.ccls.	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2006/09/24 00:36

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S81	1369	S80 "and'IDT'."	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2006/09/24 00:16
S82	333	S80 and 'IDT'	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2006/09/24 00:37
S83	63	S82 and laminat\$3	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2006/09/24 00:30
S84	2224	310/311.ccls.	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2006/09/24 00:36
S85	15	S84 and 'IDT'	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2006/09/24 00:42
S86	2541	29/25.35.ccls.	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2006/09/24 00:42
S87	83	S86 and 'IDT'	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2006/09/24 00:52
S88	1684	438/22.ccls.	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2006/09/24 01:26
S89	1	S88 and 'IDT'	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2006/09/24 00:52
S90	78	S88 and 'SAW'	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2006/09/24 01:29
S91	20	S90 and laminat\$3	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2006/09/24 00:55
S92	17	S88 and acoustic adj wave	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2006/09/24 01:30
S93	4	("6670206").URPN.	USPAT	OR	OFF	2006/09/24 01:34

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S94	10	("5918113" "6096155" "6242283" "6287894" "6310403" "6376278" "6492194" "6514789" "6534341" "6544814").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/09/24 01:35
S95	561	438/50.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/01 19:33
S96	56	S95 and saw	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/01 19:33
S97	0	("2003/0164529").URPN.	USPAT	OR	OFF	2006/10/01 19:36
S98	0	("6933164").URPN.	USPAT	OR	OFF	2006/10/01 19:37
S99	3	("5372930" "5550090" "5807758").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/10/01 19:37

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2	pressure near reduc\$3 and (SAW surface adj acoustic adj wave) and (flip-chip flip?chip flip near chip) and resin and airtight and press\$4 and laminat\$3.clm.	US-PGPUB	OR	ON	2006/10/01 19:41
L2	3	pressure and (SAW surface adj acoustic adj wave) and (flip-chip flip?chip flip near chip) and resin and airtight and press\$4 and laminat\$3.clm.	US-PGPUB	OR	ON	2006/10/01 19:41